

## Application

- RF filter for WLL (Wireless Local Loop)

## Features

- SMD filter consisting of coupled resonators with stepped impedances
- $\text{MgTiO}_3\text{-CaTiO}_3$  ( $\epsilon_r = 21$  /  $TC_f = 0 \pm 10$  ppm/K) with a coating of copper ( $10\mu\text{m}$ ) and tin ( $>5\mu\text{m}$ )
- Excellent reflow solderability, no migration effect due to copper/tin metallization

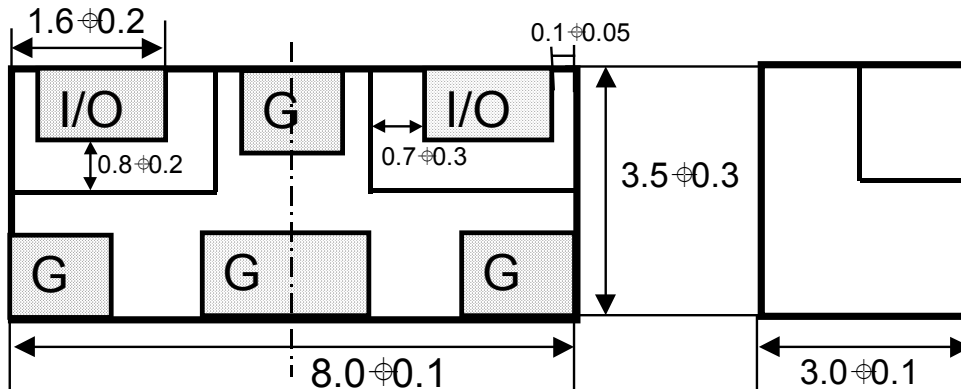
## Index

- |        |   |
|--------|---|
| Page 2 | <ul style="list-style-type: none"> <li>● Component drawing</li> <li>● Footprint</li> </ul>  |
| Page 3 | <ul style="list-style-type: none"> <li>● Characteristics</li> <li>● Maximum ratings</li> <li>● Typical passband characteristic</li> </ul> |
| Page 4 | <ul style="list-style-type: none"> <li>● Processing information</li> <li>● Soldering requirements</li> <li>● Delivery mode</li> </ul>     |

ISSUE DATE	08.04.04	ISSUE	A	PUBLISHER	SAW MWC PD	PAGE	1/4
------------	----------	-------	---	-----------	------------	------	-----

Data Sheet

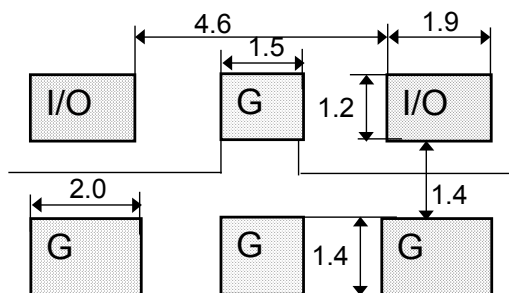
Component drawing



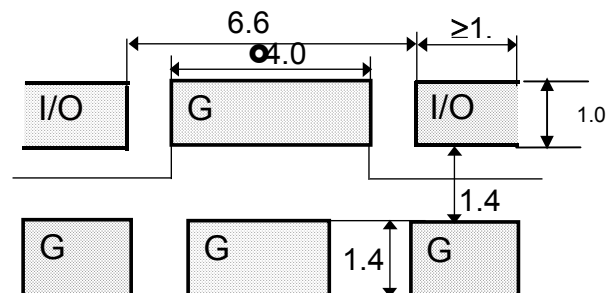
View from below onto the solder terminals and view from beside

Footprint

recommended



compatible footprint



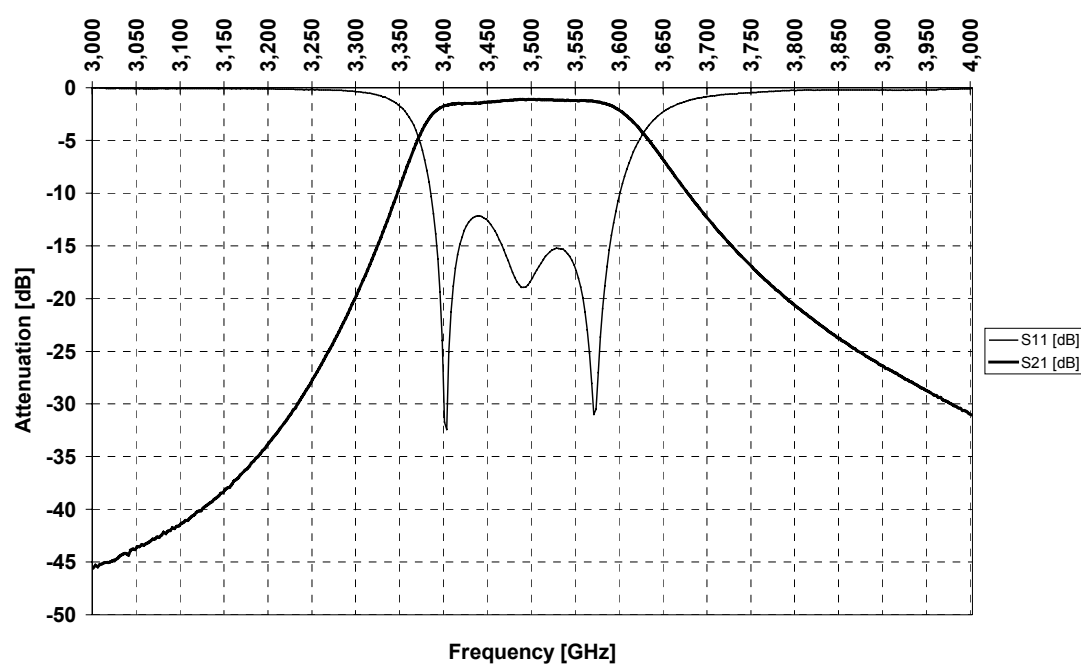
ISSUE DATE	08.04.04	ISSUE	A	PUBLISHER	SAW MWC PD	PAGE	2/4
------------	----------	-------	---	-----------	------------	------	-----

**Data Sheet**
**Characteristics**

		min.	typ.	max.	
Center frequency	$f_C$	-	3500.0	-	MHz
Insertion loss	$\alpha_{IL}$		1.2	1.8	dB
Passband	$B$	160			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$		0.5	1.0	dB
Standing wave ratio	$SWR$		1.5	2.0	
Impedance	$Z$		50		$\Omega$
Power	$P$			1.0	W
Attenuation	$\alpha$				
	at DC to 2800 MHz	40	45		dB
	at 2800 to 3240 MHz	26			dB
	at 3900 to 5000 MHz	25			dB
	at 5000 to 7200 MHz	20			dB

**Maximum ratings**

IEC climatic category (IEC 68-1)		- 40/+ 90/56	
Operating temperature	$T_{Op}$	-40 / + 85	°C

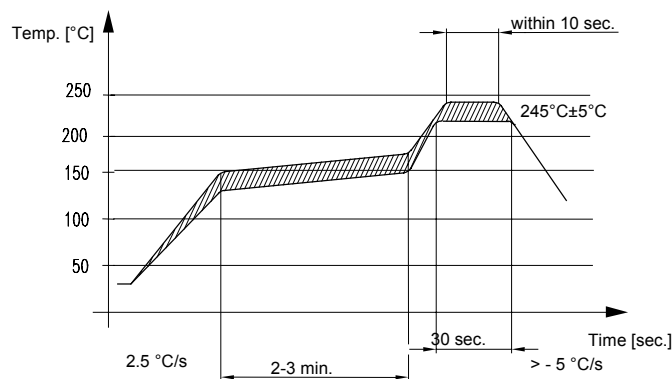
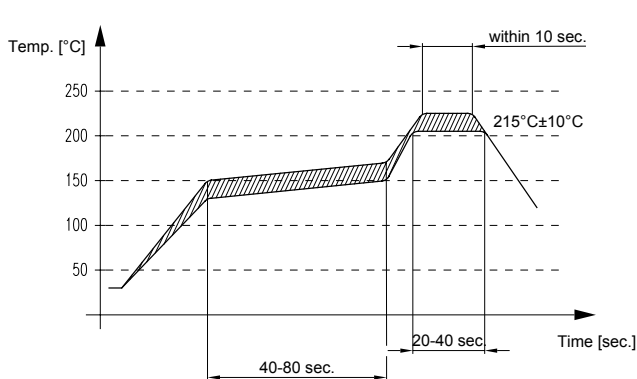
**Typical passband characteristic**


**Data Sheet**
**Processing information**

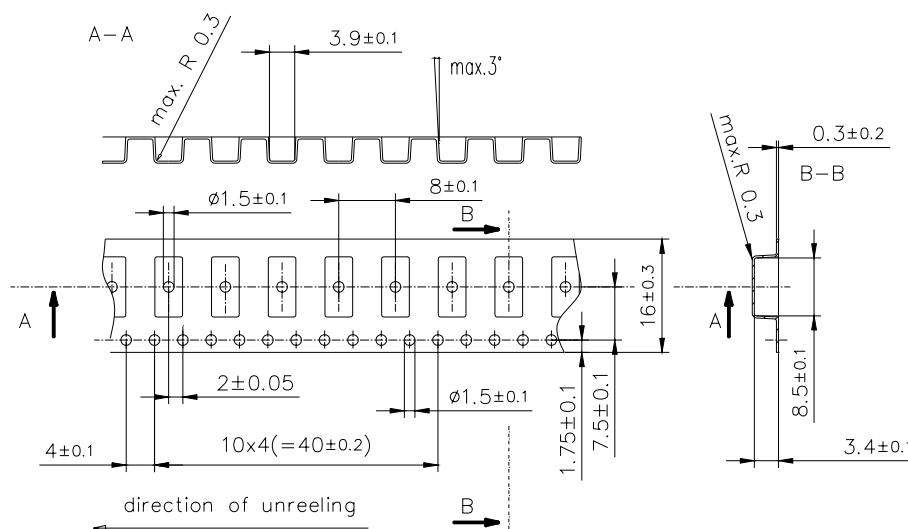
- Wettability acc to IEC 68-2-58:  $\geq 75\%$  (after aging)

**Soldering Requirements**

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	°C °C

**Recommended soldering conditions (infrared):**

**Delivery mode**

- Blister tape acc. to IEC 286-3, PS, grey
- Pieces/tape: 2000



© EPCOS AG 2001. All Rights Reserved. Reproduction, publication and dissemination of this data sheet, enclosures hereto and the information contained therein without EPCOS' prior express consent is prohibited.

The information contained in this data sheet describes the type of component and shall not be considered as guaranteed characteristics. Purchase orders are subject to the General Conditions for the Supply of Products and Services of the Electrical and Electronics Industry recommended by the ZVEI (German Electrical and Electronic Manufacturers' Association), unless otherwise agreed.

ISSUE DATE	08.04.04	ISSUE	A	PUBLISHER	SAW MWC PD	PAGE	4/4
------------	----------	-------	---	-----------	------------	------	-----